## SN54LS112A, SN54S112, SN74LS112A, SN74S112A DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

D2661, APRIL 1982-REVISED MARCH 1988

SDLS011

- Fully Buffered to Offer Maximum Isolation from External Disturbance
- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

#### description

These devices contain two independent J-K negative-edge-triggered flip-flops. A low level at the preset and clear inputs sets or resets the outputs regardless of the levels of the other inputs. When preset and clear are inactive (high), data at the J and K inputs meeting the setup time requirements are transferred to the outputs on the negative-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold time interval, data at the J and K inputs may be changed without affecting the levels at the outputs. These versatile flip-flops can perform as toggle flip-flops by tying J and K high.

The SN54LS112A and SN54S112 are characterized for operation over the full military temperature range of ~55°C to 125°C. The SN74LS112A and SN74S112A are characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each flip-flop)

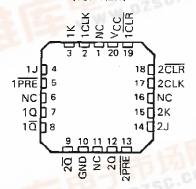
	IN	PUTS			оит	PUTS
PRE	CLR	ÇLK	J	K	a	ā
L	Н	Х	X	Х	Н	L
Н	L	×	Х	Х	Ĺ	Н
L	L	X	Х	Х	H <sup>†</sup>	H <sup>†</sup>
н	Н	1	L	L	ao	$\overline{a}_0$
[ н	Н	1	Н	L	Н	L
Н	н	1	L	Н	L	н
н	Н	1	Н	н	TOG	GLE
Н	H	Н	Х	Х	αo	₫o

<sup>†</sup> The output levels in this configuration are not guaranteed to meet the minimum levels for VOH if the lows at preset and clear are near VIL minimum. Furthermore, this configuration is nonstable; that is, it will not persist when either preset or clear returns to its inactive (high) level.

SN54LS112A, SN54S112 . . . J OR W PACKAGE SN74LS112A, SN74S112A . . . D OR N PACKAGE (TOP VIEW)

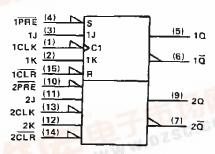
		-, .,	_	"
1CLK	1	U	16	□vcc
1K 🖺	2		15	1 CLR
1J [	3		14	2CLR
1PRE	4		13	2CLK
10[	5		12	] 2K
1₫[	6		11	2J
20 [	7		10	2PRE
GND [	8		9	] 2Q

SN54LS112A, SN54S112 . . . FK PACKAGE (TOP VIEW)



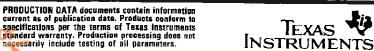
NC-No internal connection

#### logic symbol‡



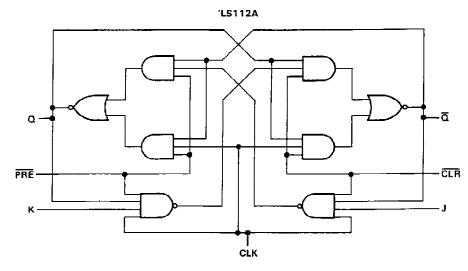
<sup>&</sup>lt;sup>‡</sup>This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

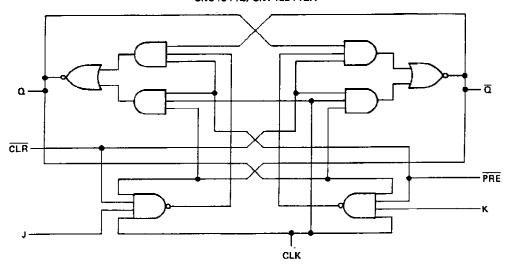


# SN54LS112A, SN54S112, SN74LS112A, SN74S112A DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

logic diagrams (positive logic)

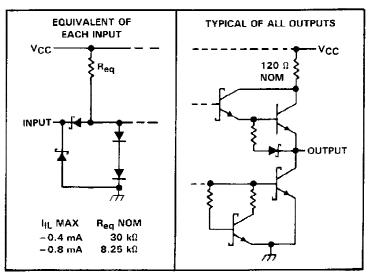


#### SN54S112, SN74LS112A

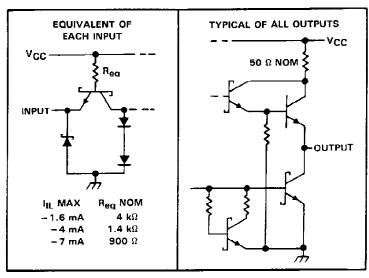


## schematics of inputs and outputs

#### 'LS112A



#### SN54S112, SN74S112A



#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)		7 V
Input voltage: 'LS112A		7 V
	S112A	
Operating free-air temperature range:	: SN54'	-55°C to 125°C
	SN74'	0°C to 70°C
Storage temperature range		-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

## SN54LS112A, SN74LS112A DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

### recommended operating conditions

			SN	154LS11	2A	SN	74LS11	2A	LIBUT	
	<u></u> .		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	٧	
VIH	High-level input voltage	·	2			2			٧	
VIL	Low-level input voltage				0.7		-	0.8	V	
ЮН	High-level output current				-0.4			-0.4	mA	
OL	Low-level output current				4			8	mA	
fclock	Clock frequency		a		30	0		30	MHz	
	Pulse duration	CLK high	20			20			⊓s	
t <sub>w</sub>	Fuise duration	PRE or CLR low	25			25	<u> </u>			
		Data high or low	20			20				
tsu	Set up time-before CLK↓	CLR inactive	25			25			ns	
		PRE inactive	20			20			1	
th	Hold time-data after CLK1		0			0			∩5	
TA	Operating free-air temperature		- 55		125	0		70	°C	

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

_	BAUETED	TEST	CONDITIONS†		SI	154LS1	I2A	SI	74LS11	2A	
PA	RAMETER	IESI	CONDITIONS		MIN	TYP	MAX	MIN	TYPI	MAX	UNIT
V <sub>IK</sub>		V <sub>CC</sub> = MIN,	I <sub>I</sub> = -18 mA				-1.5			1.5	V
Voн		V <sub>CC</sub> = MIN, I <sub>OH</sub> = -0.4 mA	V <sub>IH</sub> = 2 V,	V <sub>IL</sub> ≠ MAX,	2.5	3.4		2.7	3.4		V
1.0		V <sub>CC</sub> = MIN, I <sub>OL</sub> = 4 mA	V <sub>IL</sub> = MAX,	V <sub>IH</sub> = 2 V,		0.25	0.4		0.25	0.4	V
VOL		V <sub>CC</sub> = MIN, loL = 8 mA	V <sub>IL</sub> = MAX,	V <sub>IH</sub> = 2 V,					0.35	0.5	ľ
	J or K						0.1			0.1	<u>"</u>
4	CLR or PRE	VCC = MAX,	$V_{i} = 7 V$				0.3			0.3	mA
	CLK	1				-	0.4			0.4	
	J or K						20			20	
ΙН	CLR or PRE	V <sub>CC</sub> = MAX,	$V_{\parallel} = 2.7 V$				60			60	μА
	CLK						80			80	_
1	J or K	V <sub>CC</sub> = MAX,	Vi = 0.4 V				-0.4			-0.4	mA
IIL	All other	VCC - MAX,	V <sub>1</sub> = 0.4 V				-0.8			-0.8	
los <sup>§</sup>		V <sub>CC</sub> = MAX,	see Note 2		20		- 100	- 20		- 100	mA
ICC (T	otal)	VCC = MAX,	see Note 3			4	6		4	6	mА

<sup>&</sup>lt;sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

 $<sup>^{\</sup>ddagger}$  All typical values are at  $V_{CC}$  = 5 V,  $T_{A}$  = 25 °C.

Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

NOTES: 2. For certain devices where state commutation can be caused by shorting an output to ground, an equivalent test may be performed with  $V_0 = 2.25$  V and 2.125 V for the '54 family and the '74 family, respectively, with the minimum and maximum limits reduced to one half of their stated values.

<sup>3.</sup> With all outputs open, ICC is measured with the Q and  $\overline{Q}$  outputs high in turn. At the time of measurement, the clock input is grounded.

## SN54LS112A, SN74LS112A DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

# switching characteristics, VCC = 5 V, TA = 25 °C (see Note 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	ТҮР	мах	UNIT
f <sub>max</sub>			-	30	45		MHz
t <b>PL</b> H	CLR. PRE or CLK	Q or Q	$R_L = 2 k\Omega$ , $C_L = 15 pF$		15	20	กร
<sup>t</sup> PHL	CEN, PRE OF CER	4014			15	20	пs

NOTE 4: Load circuits and voltage waveforms are shown in Section 1.

## SN54S112, SN74S112A DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

#### recommended operating conditions

			S	N54S1	12	SI	174511	2 <b>A</b>	UNIT	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
VCC	Supply voltage	·	4.5	5	5.5	4.75	5	5.25	٧	
ViH	High-level input voltage	-	2			2			٧	
VIL	Low-level input voltage				0.8	Ī		0.8	<b>&gt;</b>	
ЮН	High-level output current				- 1			- 1	mA	
loL	Low-level output current				20			20	mΑ	
		CLK high	6			6				
tw	Pulse duration	CLK low	6.5			6.5			пѕ	
		PRE or CLR low	8			8				
t <sub>su</sub>	Set up time-before CLK1	Data high or low	7			7			กร	
th	Hold time-data after CLK1		0			0			ns	
TA	Operating free-air temperature		-55		125	0		70	°C	

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	0.4445750	7507	CONDITIONS		5	SN54S1	12	SN74S112A			11807
PARAMETER		IESI	CONDITIONS		MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIK		V <sub>CC</sub> = MIN,	I <sub>I</sub> = -18 mA				-1.2			-1.2	<b>&gt;</b>
VoH		V <sub>CC</sub> = MIN, I <sub>OH</sub> = −1 mA	V <sub>IH</sub> = 2 V,	VIL = MAX,	2.5	3.4		2.7	3.4		>
VOL		V <sub>CC</sub> = MIN, I <sub>OL</sub> = 20 mA	$V_{IH} = 2 V,$	V <sub>IL</sub> → 0.8 V,			0.5			0.5	٧
Ι <sub>Ι</sub>		V <sub>CC</sub> = MAX.	V <sub>1</sub> = 5.5 V	,			1			1	mA
	J or K	V <sub>CC</sub> = MAX.	V 27V				50			50	μΑ
ΉН	All other	T ACC = INIAV	V  = 2.7 V				100	_		100	μΓ
	JorK						-1.6			-1.6	
1	CLR <sup>§</sup>	V <sub>CC</sub> = MAX,	V A E V				<b>-7</b>			<b>-7</b>	mΑ
ΙΙΓ	PRE §	J ACC = MAY	VI = 0.5 V				<b>-7</b>			<b>-7</b>	11125
	CLK						-4			- 4	
los <sup>¶</sup>		V <sub>CC</sub> = MAX			-40		- 100	- 40		~ 100	mA
lcc#		V <sub>CC</sub> = MAX,	see Note 3			15	25		15	25	mA

<sup>&</sup>lt;sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

 $<sup>^{\</sup>ddagger}$  All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25 °C.

<sup>§</sup>Clear is tested with preset high and preset is tested with clear high.

Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

<sup>#</sup>Values are average per flip-flop.

NOTE 3: With all outputs open,  $I_{CC}$  is measured with the Q and  $\overline{Q}$  outputs high in turn. At the time of measurement, the clock input is grounded.

# switching characteristics, VCC = 5 V, TA = 25 °C (see Note 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f <sub>max</sub>				80	125		MHz
t <sub>PLH</sub>	PRE or CLR	Q or $\overline{\mathbb{Q}}$			4	7	ns
	PRE or CLR (CLK high)	Q or Q	]	_	5	7	
tPHL	PRE or CLR (CLK low)		$R_L = 280 \Omega$ , $C_L = 15 \mathrm{pF}$	F	5	7	ns
tPLH	CLK	Q or $\overline{\mathbf{Q}}$			4	7	ns
tPHL	CLK	u bru			5	7	ns

NOTE 4: Load circuits and voltage waveforms are shown in Section 1.

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26-Sep-2005

## **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
JM38510/07102BEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
JM38510/07102BFA	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30103B2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30103BEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30103BFA	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
SN54LS112AJ	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SN54S112J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SN74LS112AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS112ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS112ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS112ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS112AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS112AN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS112ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS112ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS112ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S112AD	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI
SN74S112ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S112ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S112AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74S112AN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74S112ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74S112ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S112ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54LS112AFK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS112AJ	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS112AW	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S112FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S112J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S112W	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC

<sup>(1)</sup> The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.



#### PACKAGE OPTION ADDENDUM

26-Sep-2005

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

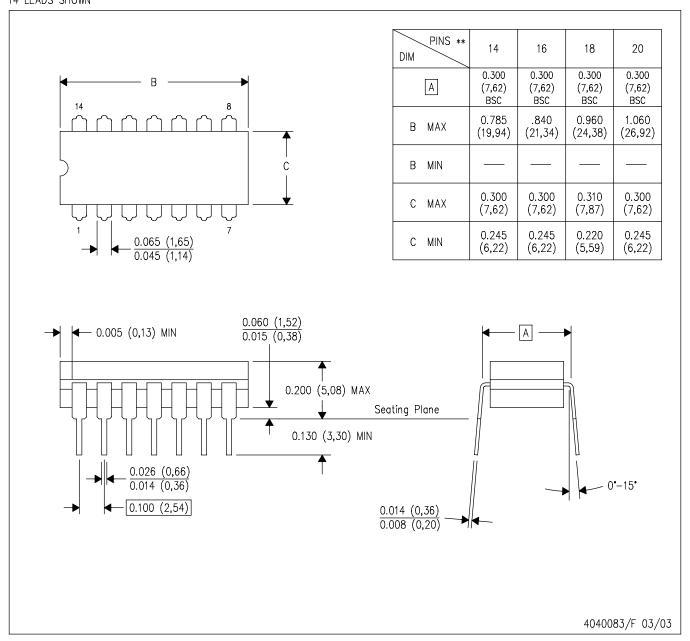
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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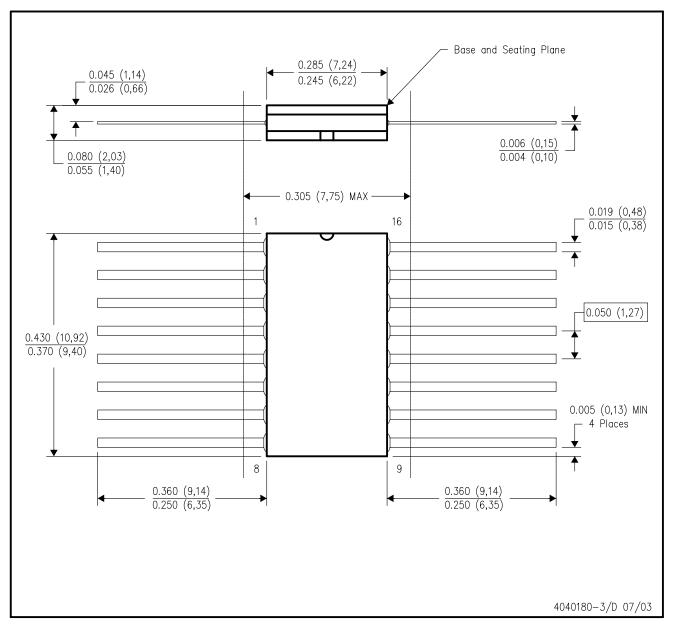
## 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

# W (R-GDFP-F16)

## CERAMIC DUAL FLATPACK



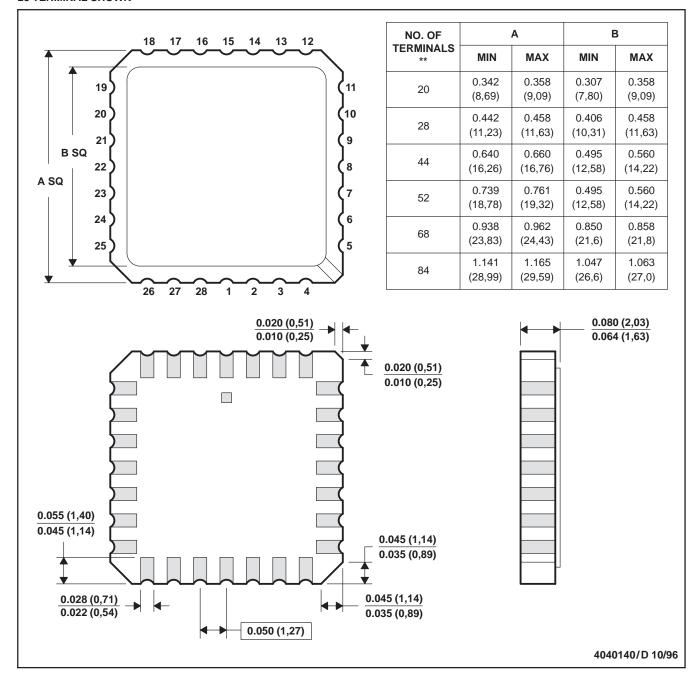
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



#### FK (S-CQCC-N\*\*)

#### **28 TERMINAL SHOWN**

#### **LEADLESS CERAMIC CHIP CARRIER**



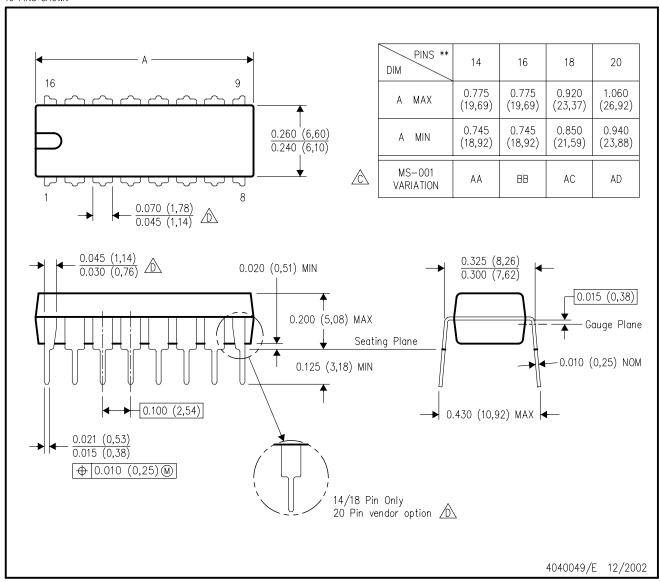
- NOTES: A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a metal lid.
  - D. The terminals are gold plated.
  - E. Falls within JEDEC MS-004



# N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

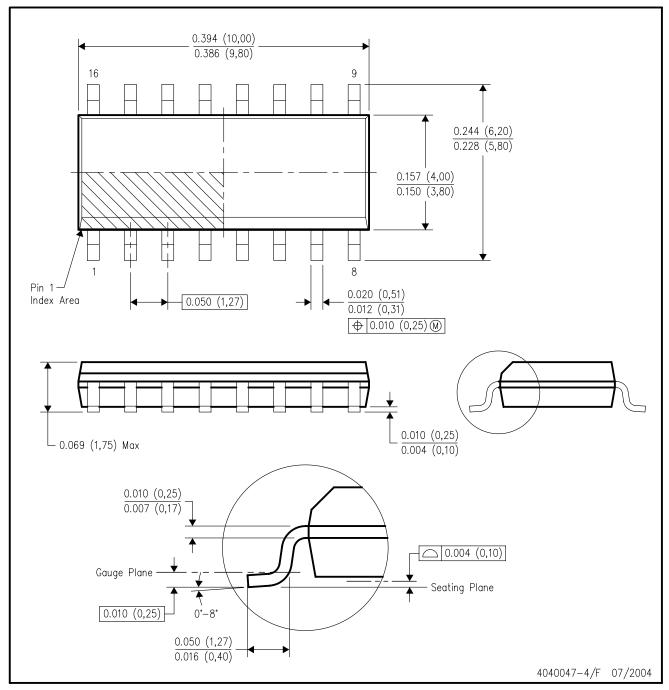
16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.

# D (R-PDSO-G16)

## PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AC.

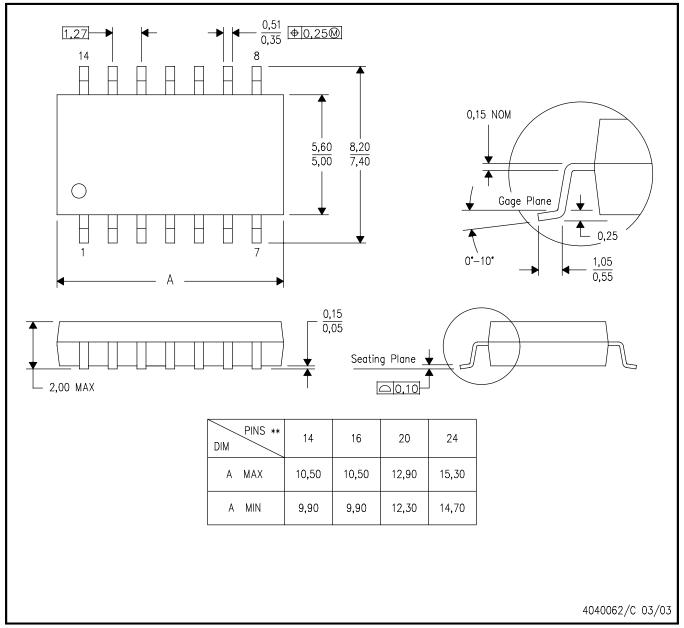


## **MECHANICAL DATA**

## NS (R-PDSO-G\*\*)

#### 14-PINS SHOWN

## PLASTIC SMALL-OUTLINE PACKAGE



- . All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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